

MATERIAL DECLARATION SHEET



Material Number	BSDW20S65C6 TO247-3			
Product Line	Semiconductor			
Compliance Date	2023-3-22			
RoHS Compliant	YES	MSL	N.A.	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	3.48	Silicon Carbide (SiC)	409-21-2	100	0.05	0.05
2	Die Attach	Silver	0.23	Diethylene Glycol Monoethyl Ether Acetate	112-15-2	5	0.00	0.06
			4.14	Silver (Ag)	7440-22-4	95	0.06	
3	Lead Frame	Copper alloy	1.46	Phosphorous (P)	7723-14-0	0.03	0.02	66.23
			4.86	Iron (Fe)	7439-89-6	0.10	0.07	
			4849.69	Copper (Cu)	7440-50-8	99.87	66.14	
4	Mold Compound	Resin	97.2	Phenol Formaldehyde resin (generic)	9003-35-4	4	1.33	33.14
			364.5	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	15	4.97	
			1798.2	Silica fused	60676-86-0	74	24.52	
			170.1	Metal hydroxide	Trade Secret	7	2.32	
5	Post-plating	Pure metal	30	Tin (Sn)	7440-31-5	100	0.41	0.41
6	Wire	Pure metal	8.1	Aluminium (Al)	7429-90-5	100	0.11	0.11
Total weight			7331.96 mg					

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(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which is exempt from the requirements